

Product Change Notification / CENO-26GCDR329

Date:						
03-Nov-2023						
Product Category:						
Driver / Interface ICs						
PCN Type:						
Manufacturing Change						
Notification Subject:						
CCB 6630 Initial Notice: Qualification of NSEB as an additional assembly site for MIC5891YWM and MIC5891YWM-TR catalog part numbers (CPN) available in 16L SOIC (.300in) package.						
Affected CPNs:						
CENO-26GCDR329_Affected_CPN_11032023.pdf CENO-26GCDR329_Affected_CPN_11032023.csv						
Notification Text:						
PCN Status:Initial Notification						
PCN Type:Manufacturing Change						
•	•	files found in the Affected CPNs se dentical files in two formats (.pdf ar				
		n additional assembly site for MIC5 in 16L SOIC (.300in) package.	891YWM and			
Pre and Post Change Summa	ry:		_			
	Pre Change	Post Change				

Asseml	oly Site	Lingsen Precision Industries, LTD.	Lingsen Precision Industries, LTD.	UTAC Thai Limited (UTL-2)		
		(LPI)	(LPI)	(NSEB)		
Wire M	1aterial	Au	Au	Au		
Die Attach	n Material	8340	8340	8200T		
_	compound erial	G600	G600	G605-L		
	Material	C194	C194	C194		
Lead-Frame	Doddle size	184x146 mils	184x146 mils	165x270 mils		
	Paddle size	See Pre and Post Change for Comparison				

Impacts to Data Sheet:None

Change ImpactNone

Reason for Change:To improve on-time delivery performance by qualifying NSEB as an additional assembly site.

Change Implementation Status:In Progress

Estimated Qualification Completion Date: March 2024

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

	November 2023			>	March 2024						
Workweek	4	4 5	4	4 7	4 8		1	1	1 2	1	1 4
Initial PCN Issue Date	Х										
Qual Report Availability										Х	
Final PCN Issue										Х	

Date Date				
Method to Identify Change:Traceability code				
Qualification Plan: Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.				
Revision History: November 3, 2023: Issued initial notification.				
The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.				
Attachments:				
PCN_CENO-26GCDR329_Pre and Post Change_Summary.pdf PCN_CENO-26GCDR329_Qual Plan.pdf				
Please contact your local Microchip sales office with questions or concerns regarding this notification.				
Terms and Conditions:				

If you wish to <u>receive Microchip PCNs via email</u> please register for our PCN email service at our <u>PCN</u> home page select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the <u>PCN FAQ</u> section.

If you wish to <u>change your PCN profile, including opt out,</u> please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

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Affected Catalog Part Numbers (CPN)
MIC5891YWM
MIC5891YWM-TR
Date: Friday, November 3, 2023